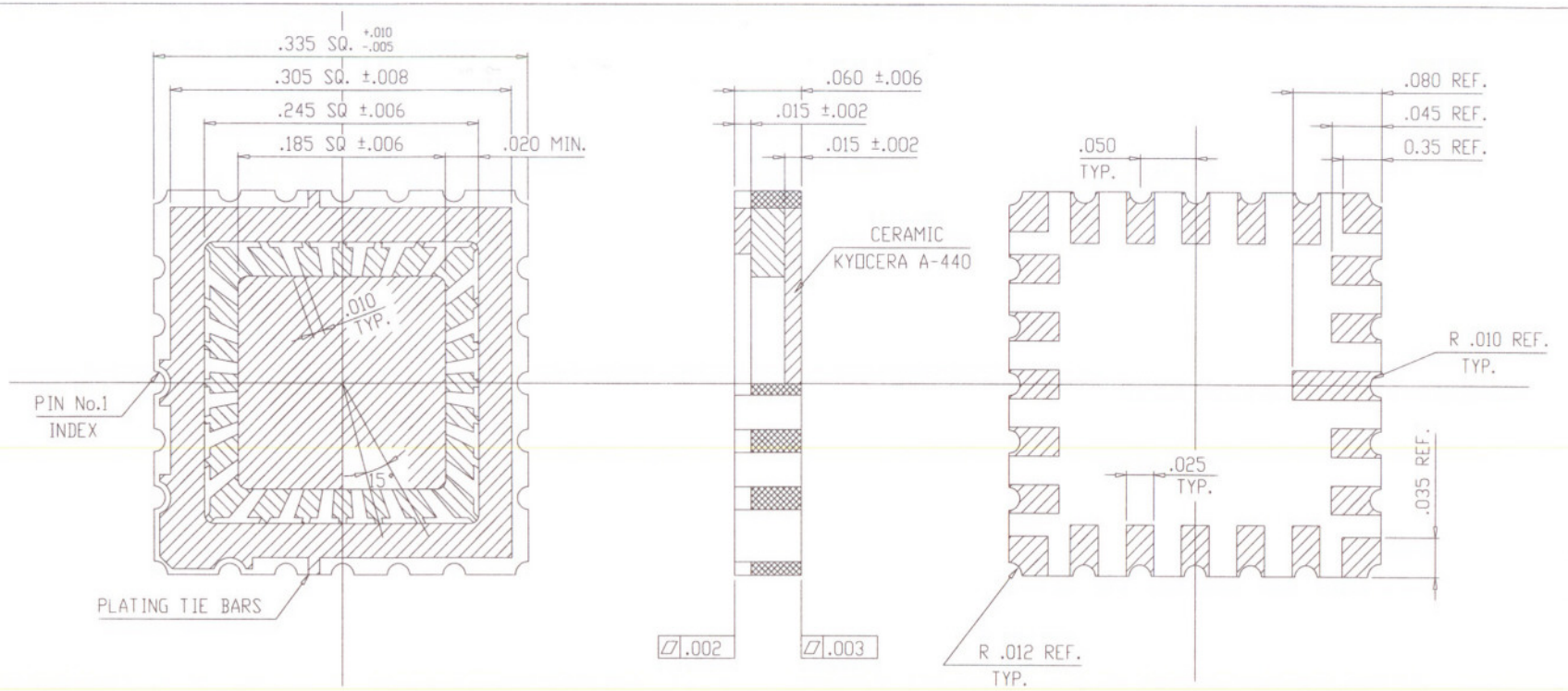
SSM P/N LCC02416



NOTES;

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCHES MIN. THICKNESS OVER NICKEL PLATED.
2. FLATNESS PERTAINS TO METALLIZED PADS ONLY.
3. NO PIN CONNECTED TO SEAL AREA AND DIE ATTACH PAD. (ZERO GROUND)

MODIFICATIONS											
					NAME 24 LEAD CHIP CARRIER		TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
					SCALE 10/1	MATERIAL AS INDICATED	±1% NLT ±.005 THIRD ANGLE PROJECTION	S.M	UE / K.H	M.S	FEB.22.'99
	CHANGE	DATE	DRAWN	CHECKED	APPROVED	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. PB-81941			SHEET /

MIC-24C

SPECTRUM SEMICONDUCTOR MATERIALS, INC. www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226